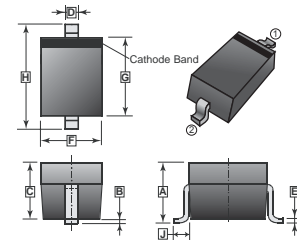


RoHS Compliant Product
A suffix of "-C" specifies halogen & lead-free

SOD-123

FEATURES

- High Current Capability
- Extremely Low Thermal Resistance
- For Surface Mount Application
- Higher Temp Soldering : 250°C for 10 Seconds at Terminals
- Low Forward Voltage



MECHANICAL DATA

- Case: Molded Plastic
- Epoxy: UL 94V-0 Rate Flame Retardant
- Lead: Solderable per MIL-STD-202, method 208 guaranteed
- Polarity: Color Band Denotes Cathode End
- Mounting Position: Any

MARKING CODE

BR

REF.	Millimeter		REF.	Millimeter	
	Min.	Max.		Min.	Max.
A	0.95	1.35	F	1.40	1.80
B	0.10	REF.	G	2.55	2.85
C	1.05	1.15	H	3.55	3.85
D	0.30	0.78	J	-	-
E	0.08	0.25			

MAXIMUM RATINGS AND ELECTRICAL CHARACTERISTICS (T_A=25°C unless otherwise specified)

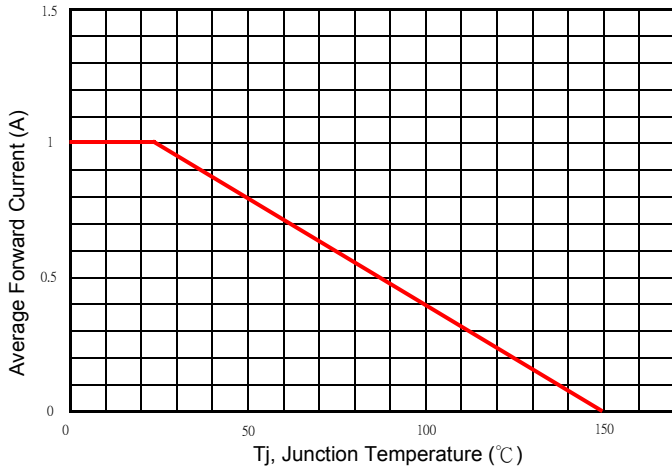
PARAMETER	SYMBOL	RATING	UNITS
Maximum Recurrent Peak Reverse Voltage	V _{RRM}	20	V
Working Peak Reverse Voltage	V _{RWM}	20	V
Maximum DC Blocking Voltage	V _R	20	V
Average Forward Current @ T _J =25°C	I _{F(AV)}	1	A
Peak Forward Current @ 8.3 ms Half Sine	I _{FSM}	10	A
Maximum Instantaneous Forward Voltage I _{FM} = 1 A, T _A = 25°C	V _{F1}	0.45	V
Maximum Instantaneous Forward Voltage I _{FM} = 1 A, T _A = 125°C	V _{F2}	0.38	V
Maximum DC Reverse Current At Rated DC Blocking Voltage @ T _J = 25°C	I _{R1}	0.1	mA
Maximum DC Reverse Current At Rated DC Blocking Voltage @ T _J = 125°C	I _{R2}	5	mA
Typical Junction Capacitance (Note 1)	C _J	210	pF
Typical Thermal Resistance (Note 2)	R _{θJA}	310	°C/W
Operating Temperature Range	T _J	150	°C
Storage temperature	T _{STG}	150	°C

Notes:

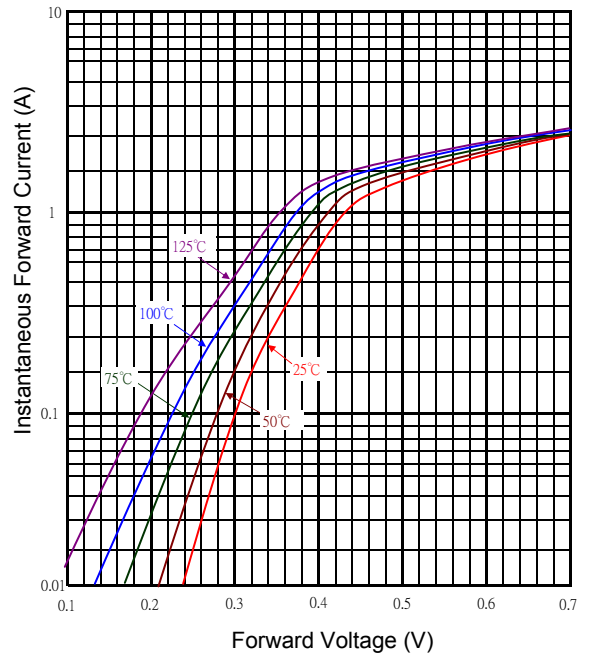
1. Measured at 1MHz and applied reverse of 0V DC.
2. FR-4 PCB, 2 oz. 0.7mm × 1.2mm copper pad.

RATINGS AND CHARACTERISTIC CURVES

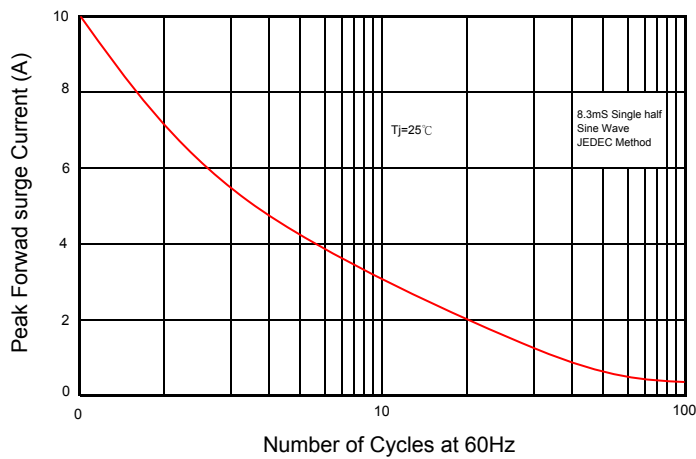
Typical Forward Current Derating Curve



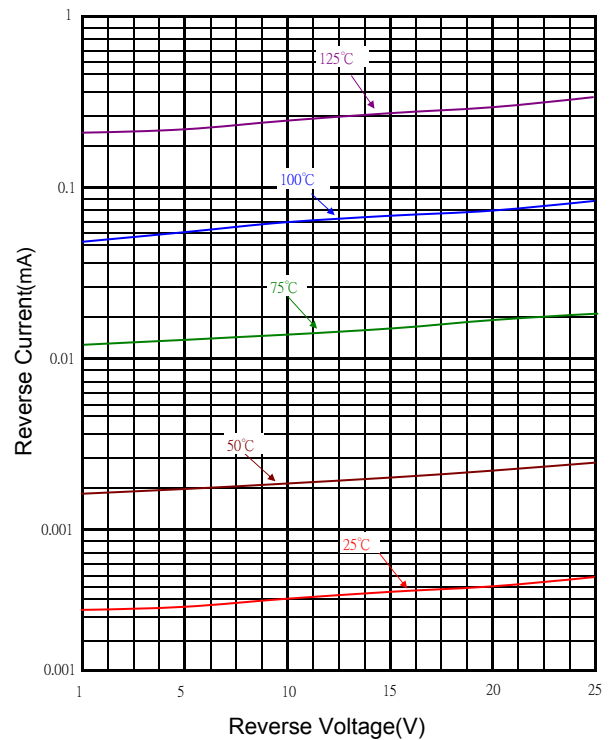
Typical Forward Characteristic



Maximum Non- Repetitive Forward Surge Current



Typical Reverse Characteristic



Typical Junction Capacitance

